ALPHA & OMEGA SEMICONDUCTOR

AON7408

30V N-Channel MOSFET

General Description

• The AON7408 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in general purpose applications.

• RoHS and Halogen-Free Compliant

Product Summary

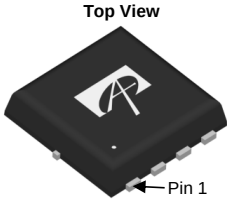
V_{DS}	30V
I_D (at V_{GS}=10V)	18A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 20mΩ
$R_{DS(ON)}$ (at V_{GS}=4.5V)	< 32mΩ

100% UIS Tested
100% R_g Tested

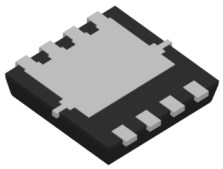
Green Product

DFN 3x3 EP

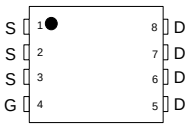
Top View

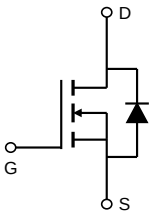


Bottom View



Top View





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current [B]	T_C=25°C	I_D	18	A
	T_C=100°C		11.5	
Pulsed Drain Current [C]		I_{DM}	64	
Continuous Drain Current [A]	T_A=25°C	I_{DSM}	10	A
	T_A=70°C		8	
Power Dissipation [B]	T_C=25°C	P_D	11	W
	T_C=100°C		4.5	
Power Dissipation [A]	T_A=25°C	P_{DSM}	3.1	W
	T_A=70°C		2	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	25	40	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		62	75	°C/W
Maximum Junction-to-Case [B]	Steady-State	$R_{\theta JC}$	8.8	11	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250µA	1.5	2.1	2.6	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V	64			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=10A		15.3	20	mΩ
		T_J=125°C		23.3	30	
		V_{GS}=4.5V, I_D=5A		22.7	32	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=10A		17		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.75	1	V
I_S	Maximum Body-Diode Continuous Current				12	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		373	448	pF
C_{oss}	Output Capacitance			67		pF
C_{rss}	Reverse Transfer Capacitance			41		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	0.6	1.8	2.8	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=15V, I_D=10A		7.1	11	nC
Q_g(4.5V)	Total Gate Charge			3.5	6	nC
Q_{gs}	Gate Source Charge			1.2		nC
Q_{gd}	Gate Drain Charge			1.6		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=1.5Ω, R_{GEN}=3Ω		4.3		ns
t_r	Turn-On Rise Time			2.8		ns
$t_{D(off)}$	Turn-Off DelayTime			15.8		ns
t_f	Turn-Off Fall Time			3		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=10A, dI/dt=100A/µs		10.5	12.6	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=10A, dI/dt=100A/µs		4.5		nC

A: The value of $R_{\theta JA}$ is measured with the device in a still air environment with T_A =25° C. The power dissipation P_{DSM} and current rating I_{DSM} are based on $T_{J(MAX)}$=150° C, using t ≤ 10s junction-to-ambient thermal resistance.
B. The power dissipation P_D is based on $T_{J(MAX)}$=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C: Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150° C.
D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300 µs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=150° C. The SOA curve provides a single pulse rating.
G. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.
H. The maximum current rating is limited by bond-wires.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

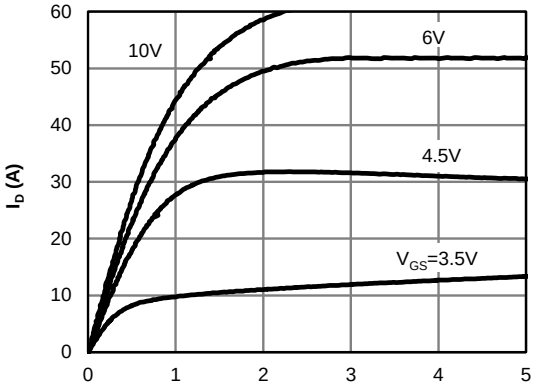


Fig 1: On-Region Characteristics

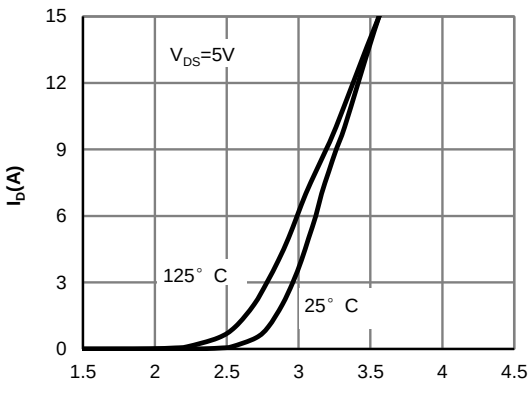


Figure 2: Transfer Characteristics

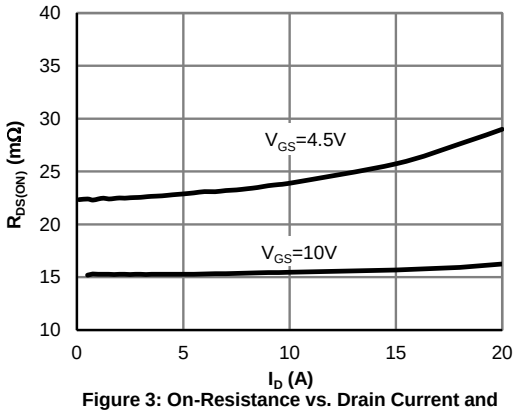


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

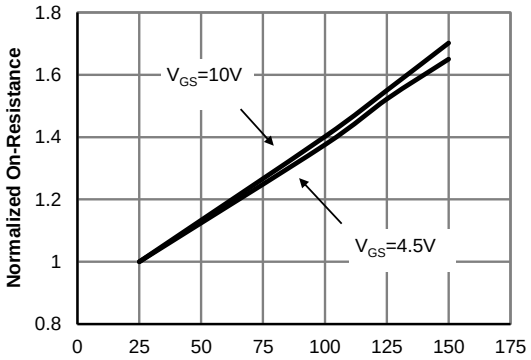


Figure 4: On-Resistance vs. Junction Temperature

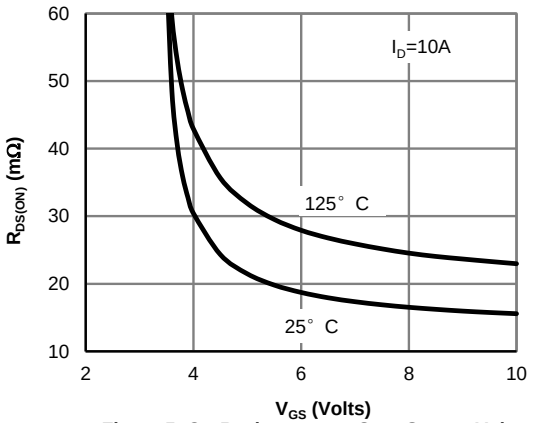


Figure 5: On-Resistance vs. Gate-Source Voltage

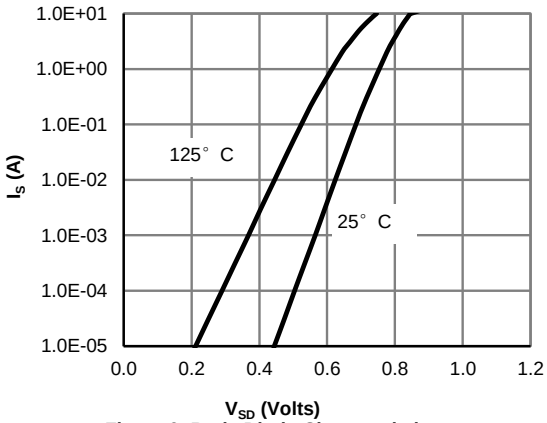


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

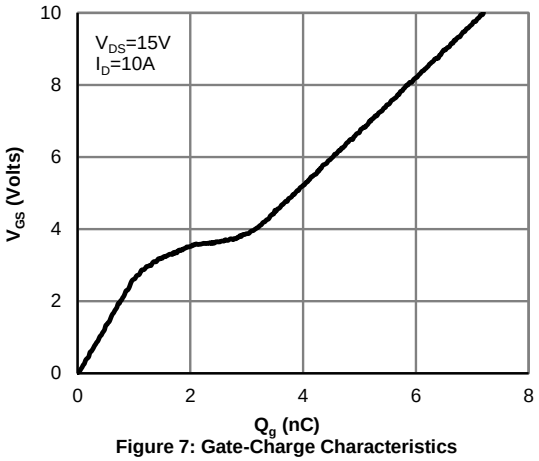


Figure 7: Gate-Charge Characteristics

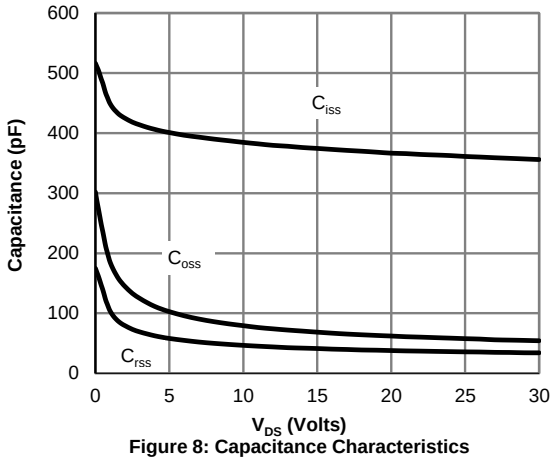


Figure 8: Capacitance Characteristics

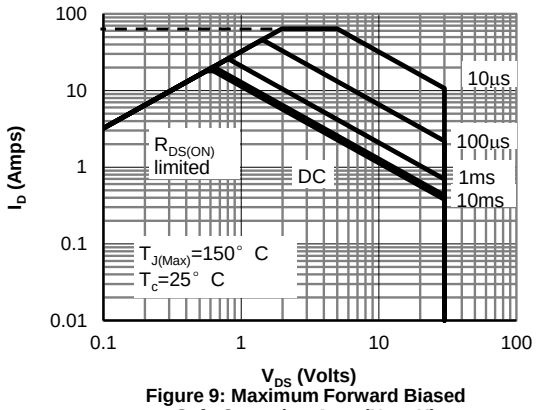


Figure 9: Maximum Forward Biased Safe Operating Area (Note H)

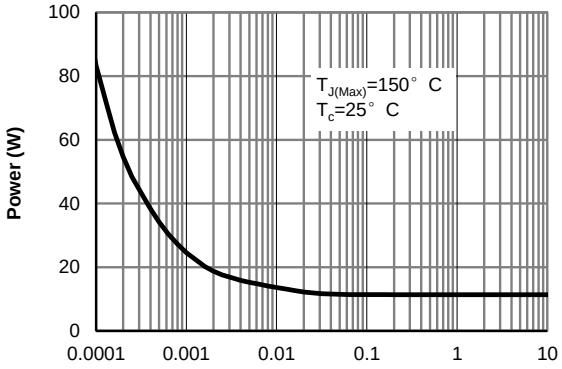


Figure 10: Single Pulse Power Rating Junction-to-C (Note F)

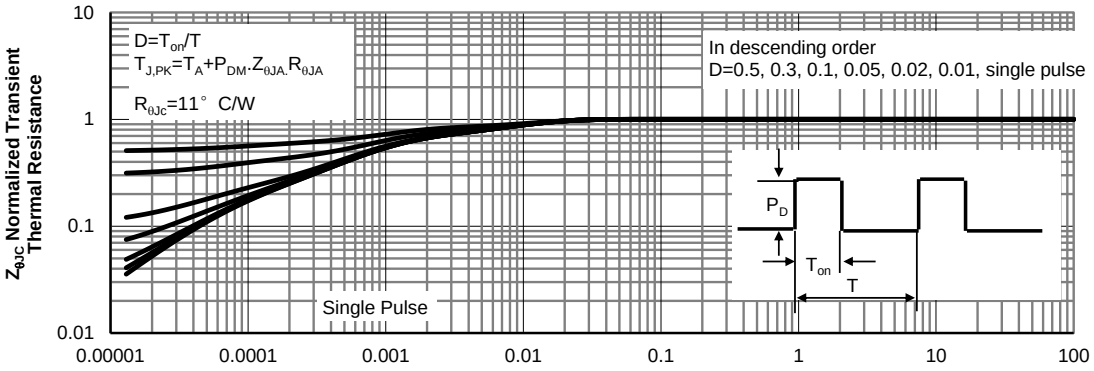


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

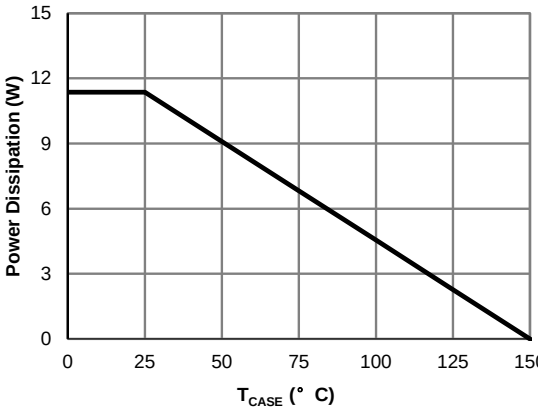


Figure 12: Power De-rating (Note F)

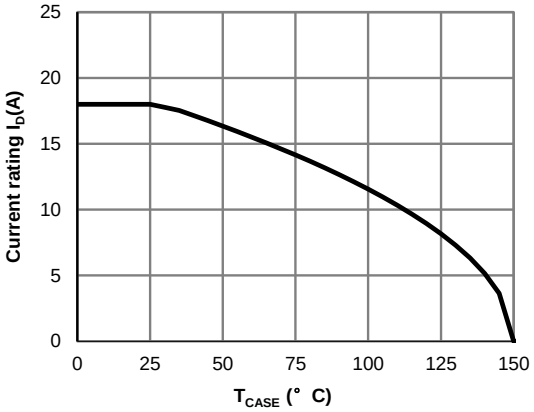


Figure 13: Current De-rating (Note F)

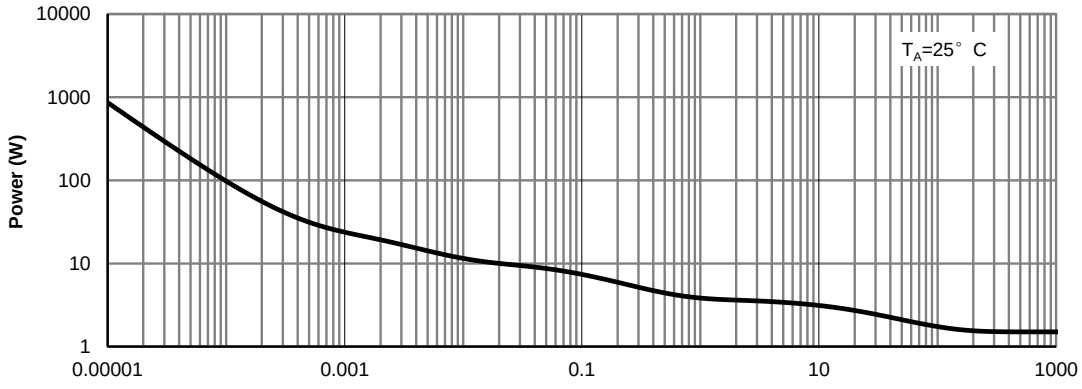


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

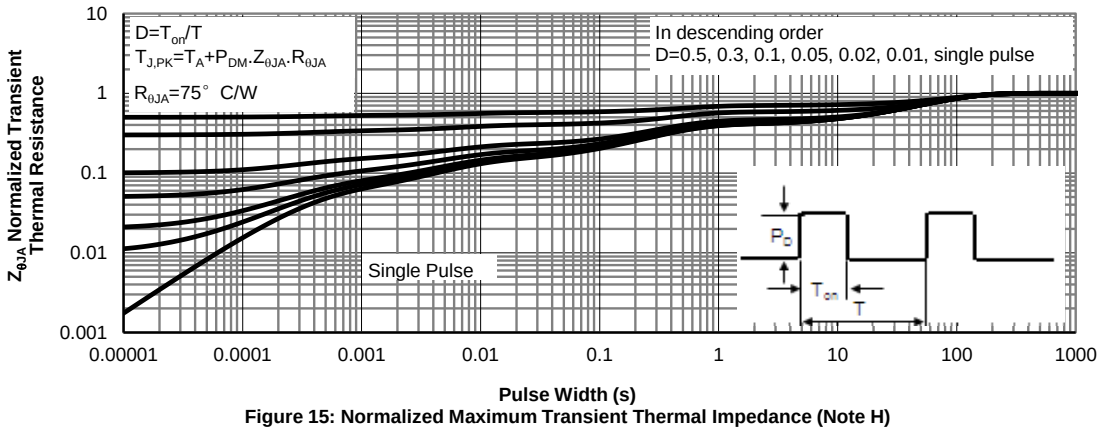
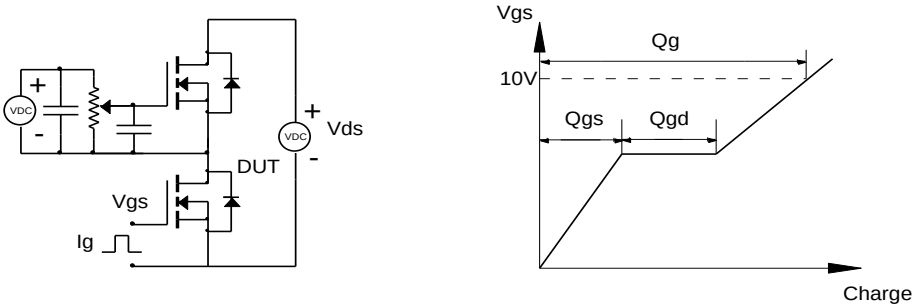
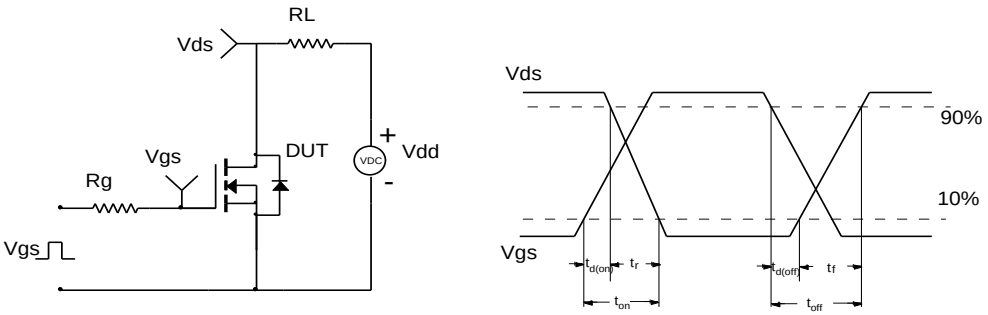


Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

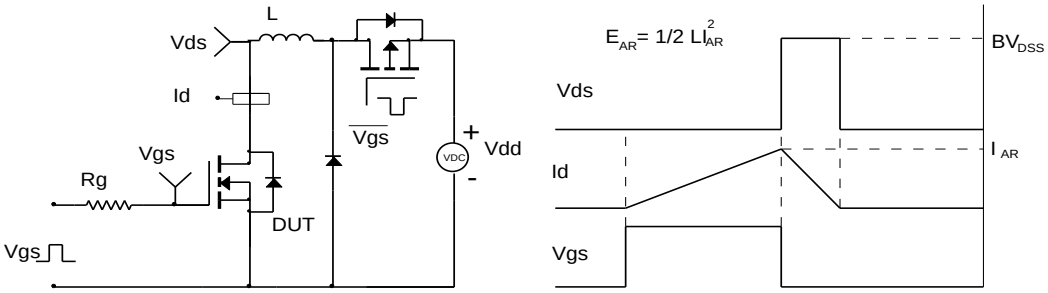
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms